GFL 1800 SL
Gap Filler Liquid

Benefits

- Room temperature curing
- Higher thermal conductivity in comparison to potting material
- Usage for Encapsulation, electromagnetic coils and applications with small fabrication tolerances
- Low Viscosity Gap Filler Liquid

Properties	Unit	GFL 1800 SL
Colour		green, white
Basic material		silicone
Mixing ratio		1:1
Curing	°C	1h ; 25 °C
Thermal Properties*		
Thermal resistance R_{th}	K/W	1.38
Thermal conductivity λ	W/mK	1.8
Electrical Properties**		
Dielectric breakdown voltage $U_{d;\,ac}$	kV	7.5
Mechanical Properties		
Hardness	Shore 00	55 - 75
Physical Properties		
Application temperature	°C	-40 to +200
Density	g/cm³	2.3
Viscosity***	Pas	2 - 8
Total mass loss (TML)	Ma. -%	< 0.17
Flame rating	UL-94	V - 0
Possible thickness	mm	0.2 - 5.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm *** Shear rate 4.6s^{-1} / 25°C